

**Machine Name : Fully automatic wafer grinding machine**

**Brand : DISCO**

**Machine Model : DFG8560**

**Stock No. : 88066**

**Ex-factory Date : To be supplemented**



**Main Technical Parameters:**

Object of action: Wafer

Maximum machining wafer size:  $\Phi 300\text{mm}$

spindle: 2

Number of chuck gauges: 3

Compatible models: DFG800 SEREINes

Overall Footage: approximately 1400\*3190\*1800mm

grinding wheel specification: Diamond grinding wheel, with a diameter up to 300mm

Rated output power: 4.8kW

Grinding speed range: 1000-7000Rpm(under normal circumstances

Grinding precision

- ① Thickness error within a single wafer: extremely small, usually controlled at the micrometer level, such as below  $1.5\mu\text{m}$
- ② Thickness error between wafers: It is also controlled at the micrometer level to ensure that the wafers processed in batches have consistent thickness
- ③ Surface roughness: The  $R_y$  value can reach  $0.13\mu\text{m}$  (completed with #2000 grinding wheel) or  $0.15\mu\text{m}$  (completed with #1400 grinding wheel).



